

**Amendments to the Specification:**

Please replace the paragraph at p. 4, lines 16-29 with the following text:

Other structures for connecting the transmission line to the waveguide have also been disclosed in ~~German Patent No. DE~~ 4,208,058 and in U. S. Patent No. 5,793,263, according to which the signals of a microstrip line are connected to the waveguide through an opening formed in the grounded layer and through a dipole antenna formed on the surface of a dielectric. According to these constructions, the waveguide is coupled by adjusting the length of the dipole antenna to meet the transmission frequency. Being affected by the thickness of the dielectric layer under the opening and by the length of the dipole antenna, therefore, it is difficult to strictly control the length of the antenna at the time of manufacturing and, hence, characteristics vary to a large extent.

Please replace the paragraph at p. 11, lines 16-26 with the following text:

In the wiring board (high-frequency package A1) of the present invention to which the waveguide B1 is connected as shown in Fig. 1b, the signals of the signal transmission line 5 connected to the high-frequency device 4 in the cavity 3 are electromagnetically coupled to the slot 6 formed in the grounded layer 7, rendered to be continuous and smooth for their electromagnetic field of signals, which propagate from the slot 6 to the waveguide B1, due to the patch conductor 10, and are transmitted to the waveguide B1 passing through the second dielectric block (second dielectric portion) 11. The patch conductor works to separate the electromagnetic waves into both sides thereof, instead of concentrating the electric

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current which is done by the antennas disclosed in DE 4,208,058 and USP U.S.  
Patent No. 5,793,263.